



AF 1.

#12

**IN THE UNITED STATES PATENT AND TRADEMARK OFFICE**

In re Application of:

Box: AF

Mark NEUSCHUTZ et al

Examiner: Nihir B. Patel

Serial No.: 09/876,227

Group Art Unit: 3743

Filed: June 8, 2001

For: **USE OF PCMS IN HEAT SINKS FOR ELECTRONIC COMPONENTS**

**RECEIVED**

APR 04 2003

TECHNOLOGY CENTER R3700

**AMENDMENT UNDER 37 C.F.R. §1.116**

Assistant Commissioner for Patents  
Washington, D.C. 20231

Sir:

In response to the Office Action dated December 31, 2002, Applicants hereby respond with the following remarks.

**REMARKS**

**Prior Art Rejections**

The Examiner has maintained his rejection of claims 1-16 in view of the teachings of Laing ('356). Applicants respectfully request reconsideration of the rejection in view of the arguments for patentability made below.

Laing discloses a cooling device for a semiconductor apparatus comprising a chamber enclosing a non-metallic crystal forming material which can undergo a phase change at a temperature which corresponds to the desired operating temperature of the semiconductor component. More specifically, the semiconductor component that is in heat conductive